

WHAT IS CLAIMED IS:

5        1. A flexible board comprising:  
          (a) an internal layer;  
          (b) a line formed in a first area of said internal layer, said line radiating unnecessary radiation;  
          (c) a first ground layer formed on an upper surface of said internal layer, said first ground layer disallowing radiation to pass therethrough; and  
          (d) a second ground layer formed a lower surface of said internal layer, said 10 second ground layer disallowing radiation to pass therethrough.

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15        2. The flexible board as set forth in claim 1, further comprising:

      (e) a first cover layer formed over a surface of said first ground layer; and  
      (f) a second cover layer formed over a surface of said second ground layer.

3. The flexible board as set forth in claim 2, further comprising electrically insulating adhesive layers sandwiched among said internal layer, said first and second ground layers, and said first and second cover layers.

20        4. The flexible board as set forth in claim 1, further comprising a ground line formed in a second area except said first area in said internal layer.

25        5. The flexible board as set forth in claim 1, wherein a plurality of through-holes is formed throughout said first ground layer, said internal layer, and said second ground layer.

6. The flexible board as set forth in claim 4, wherein a plurality of through-holes is formed throughout said first ground layer, said ground line, and said second ground layer, said through-holes electrically connecting said first ground

layer, said ground line, and said second ground layer to one another.

7. A method of fabricating a flexible board, comprising the steps of:

- (a) forming a line in a first area of an internal layer, said line radiating unnecessary radiation;
- (b) covering an upper surface of said internal layer with a first ground layer which disallows radiation to pass therethrough; and
- (c) covering a lower surface of said internal layer with a second ground layer which disallows radiation to pass therethrough.

8. The method as set forth in claim 7, further comprising the steps of:

- (d) covering a surface of said first ground layer with a first cover layer; and
- (e) covering a surface of said second ground layer with a second cover layer.

15 9. The method as set forth in claim 8, further comprising the step of forming electrically insulating adhesive layers among said internal layer, said first and second ground layers, and said first and second cover layers.

20 10. The method as set forth in claim 7, further comprising the step of forming a ground line in a second area except said first area in said internal layer.

25 11. The method as set forth in claim 7, further comprising the step of forming a plurality of through-holes throughout said first ground layer, said internal layer, and said second ground layer.

12. The method as set forth in claim 10, further comprising the step of forming a plurality of through-holes throughout said first ground layer, said ground line, and said second ground layer so that said through-holes electrically connect said first ground layer, said ground line, and said second ground layer to

one another.

13. A cellular phone including a flexible board,  
said flexible board comprising:

(a) an internal layer;

(b) a line formed in a first area of said internal layer, said line radiating unnecessary radiation;

(c) a first ground layer formed on an upper surface of said internal layer, said first ground layer disallowing radiation to pass therethrough; and

10 (d) a second ground layer formed a lower surface of said internal layer, said second ground layer disallowing radiation to pass therethrough.

14. The cellular phone as set forth in claim 13, further comprising:

(e) a first cover layer formed over a surface of said first ground layer; and

(f) a second cover layer formed over a surface of said second ground layer.

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16. The cellular phone as set forth in claim 13, further comprising a ground line formed in a second area except said first area in said internal layer.

25 17. The cellular phone as set forth in claim 13, wherein a plurality of through-holes is formed throughout said first ground layer, said internal layer, and said second ground layer.

18. The cellular phone as set forth in claim 16, wherein a plurality of through-holes is formed throughout said first ground layer, said ground line, and

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said second ground layer, said through-holes electrically connecting said first ground layer, said ground line, and said second ground layer to one another.